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IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

Applicant : Min-Lung HUANG Confirmation No: 8686
Appl. No. : 10/820,856
Filed : April 9, 2004
Title : Under Bump Metallization Structure Of A Semiconductor Wafer

TC/A.U. : 2813
Examiner : D. S. Bryant

Docket No.: : HUAN3261/REF
Customer No: : 23364

RESPONSE TO ELECTION REQUIREMENT

Commissioner for Patents
P.O. Box 1450
Alexandria, VA 22313-1450

Sir:

This is in response to the Official Action of March 9, 2006, in connection with the above identified application.


The Official Action is an election requirement in which it is urged that there are two separate and distinct species claimed in this application. It is further indicated that no claims are found to be generic. Applicant elects the species (I) pertaining to an under bump metallization structure applicable to be disposed on the bonding pads of a semiconductor wafer wherein an adhesive layer, first barrier layer, a wetting layer and a second barrier layer are utilized. Claims 1 through 7 are readable on the elected species. Applicants reserve the right to file one or more divisional applications on the non-elected inventions at a later time.

Appl. No. 10/820,856
Amendment dated: April 7, 2006
Reply to OA of: March 30, 2006

In view of the election of the species (I), without traverse, an early and favorable action on the merits is now believed to be in order and is most respectfully requested.

Respectfully submitted,

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April 7, 2006